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News Release

JX Nippon Mining & Metals Corporation

Start of Sales of Ultra-Thin Treated Rolled Copper Foil

JX Nippon Mining & Metals Corporation (head office: Otemachi 2-chome, Chiyoda-ku, Tokyo; president: Yoshimasa Adachi) is pleased to announce it has successfully developed ultra-thin treated rolled copper foil with thicknesses of 6 and 9 μm and started sales on a full-fledged basis.

JX Nippon Mining & Metals has long manufactured and sold treated rolled copper foil with a thickness of up to 12 μm . As the parts used in smartphones and tablet PCs become smaller and smaller, however, demand has grown recently for ultra-thin treated rolled copper foil that can tolerate the same rigorous folding and bending processes as foil of conventional thicknesses.

We have created a system to commercially produce ultra-thin treated rolled copper foil with thicknesses of 6 and 9 μm that is equivalent in quality, including surface uniformity and flat configuration, to foil with a conventional thickness. We were able to achieve this by improving rolling technologies as well as the nodulation process of the copper foil surface and developing new nodulation technologies.

Ultra-thin treated rolled copper foil makes possible very minute processing that has been impossible with foil of conventional thicknesses, and new applications are expected.